12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20250618010.1
BQ2969/T Die Revision Change, Pin 1 Orientation Change, and Datasheet Update
Change Notification / Sample Request

Date: June 18, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20250618010.1
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
BQ296900DSGR	NULL
BQ296901TDSGR	NULL
BQ296900TDSGR	NULL
BQ296907DSGR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250618010.1	**PCN Date:**	June 18, 2025
Title:	BQ2969/T Die Revision Change, Pin 1 Orientation Change, and Datasheet Update		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	September 16, 2025	**Sample requests accepted until:**	August 17, 2025*

***Sample requests received after August 17, 2025 will not be supported.**

Change Type:

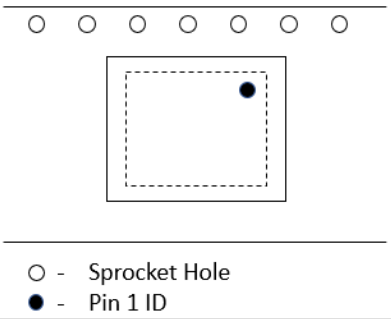
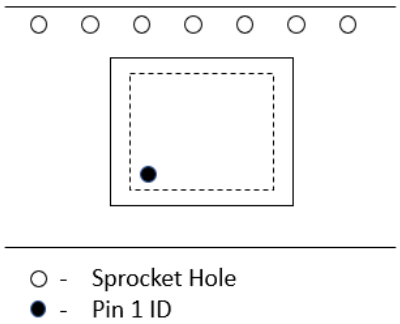
☐	Assembly Site	☒	Design	☐	Wafer Bump Material
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Materials
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

This notification is to inform of a design change to the BQ2969 and BQ2969T family of devices. This is a design change to change the operation of the OverVoltage delay timer.

The Pin 1 Orientation change from Quadrant 2 to Quadrant 3. See diagrams below:

	Current	**Proposed**
Pin 1 Orientation		
Pin 1 Quadrant	2	**3**

The product datasheet is updated as seen in the change revision history below:

TEXAS INSTRUMENTS — **BQ2969**
SLUSF53B – AUGUST 2024 – REVISED JUNE 2025

Changes from Revision A (May 2025) to Revision B (June 2025)	**Page**
• Changed BQ296909 to active in the *Device Comparison Table*	3

Changes from Revision * (August 2024) to Revision A (May 2025)	**Page**
• Added BQ296901, BQ296902, BQ296909, and BQ296910 to the *Device Comparison Table*	3
• Updated t_{DELAY_RESET} description in *Electrical Characteristics*	4
• Added clarification information in *Detailed Design Procedure*	15

TEXAS INSTRUMENTS — **BQ2969T**
SLUSFQ8A – DECEMBER 2024 – REVISED MAY 2025

Changes from Revision * (December 2024) to Revision A (May 2025)	**Page**
• Added BQ296906T in the *Device Comparison Table*	4
• Updated the Test Conditions for the OV Delay Reset Time in *Electrical Characteristics*	5
• Added clarification information in *Detailed Design Procedure*	17

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
BQ2969	SLUSF53	**SLUSF53A**	http://www.ti.com/product/BQ2969
BQ2969T	SLUSFQ8	**SLUSFQ8A**	http://www.ti.com/product/BQ2969T

Qual details are provided in the Qual Data Section.

Reason for Change:

Customer request

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Change in hysteresis activation behavior

Product Affected:

BQ296900DSGR	BQ296900DSGR.A	BQ296900TDSGR	BQ296900TDSGR.A
BQ296901TDSGR	BQ296901TDSGR.A	BQ296907DSGR	BQ296907DSGR.A

Qualification Report

Approve Date May 7, 2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: BQ296900DSGR	Qual Device: BQ296907DSGR	Qual Device: BQ296900TDSGR	Qual Device: BQ296901TDSGR	QBS Reference: BQ79600PWRQ1	QBS Reference: TLV9062IDSGR	QBS Reference: BQ296900DSGR	QBS Reference: TPS37A010122DSKRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	3/231/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/231/0	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	192 Hours	-	-	-	-	-	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	3/231/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	-	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/135/0	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	-	3/231/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	3/231/0	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/2400/0	3/2400/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	-	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	3/30/0	-	-	3/30/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	1/3/0	-	-	-	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	1/3/0	-	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	1/3/0	-	-	-	1/3/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	1/30/0	-	2/60/0	1/30/0	1/30/0	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device BQ296900DSGR is qualified at MSL1 260C
- Qual Device BQ296907DSGR is qualified at MSL1 260C
- Qual Device BQ296900TDSGR is qualified at MSL1 260C
- Qual Device BQ296901TDSGR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2502-009

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.